


**Description**

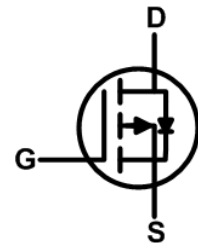
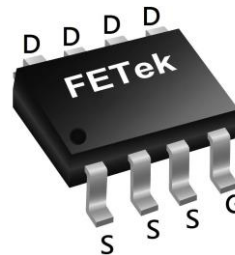
- ★ Advanced Trench MOS Technology
- ★ 100% EAS Guaranteed
- ★ Green Device Available

**Product Summary**

BVDSS	RDSON	ID
-150V	780mΩ	-1.1A

**Applications**

- ★ Load Switch.
- ★ Power Management.
- ★ LED Backlighting.
- ★ Networking application.

**SOP8 Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-1.1	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-0.88	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-4.4	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	12.5	mJ
$I_{AS}$	Avalanche Current	5	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>4</sup>	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	40	$^\circ C/W$

**Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-150	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10V, I_D=-1A$	---	650	780	m $\Omega$
		$V_{GS}=-6V, I_D=-0.5A$	---	700	980	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-2.0	-3.0	-4.0	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-120V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	uA
		$V_{DS}=-120V, V_{GS}=0V, T_J=85^\circ C$	---	---	30	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	12	---	$\Omega$
$Q_g$	Total Gate Charge	$V_{DS}=-75V, V_{GS}=-10V, I_D=-1A$	---	10.8	---	nC
$Q_{gs}$	Gate-Source Charge		---	3.1	---	
$Q_{gd}$	Gate-Drain Charge		---	2.2	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-30V, V_{GS}=-10V, R_G=6\Omega, I_D=-1A$	---	21	---	ns
$T_r$	Rise Time		---	16	---	
$T_{d(off)}$	Turn-Off Delay Time		---	40	---	
$T_f$	Fall Time		---	18	---	
$C_{iss}$	Input Capacitance	$V_{DS}=-75V, V_{GS}=0V, f=1MHz$	---	706	---	pF
$C_{oss}$	Output Capacitance		---	23	---	
$C_{rss}$	Reverse Transfer Capacitance		---	13	---	

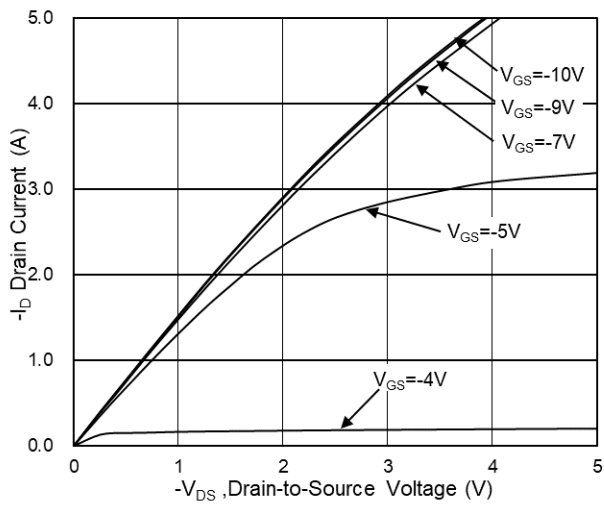
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$ , Force Current	---	---	-1	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=-1A, T_J=25^\circ C$	---	---	-1.2	V

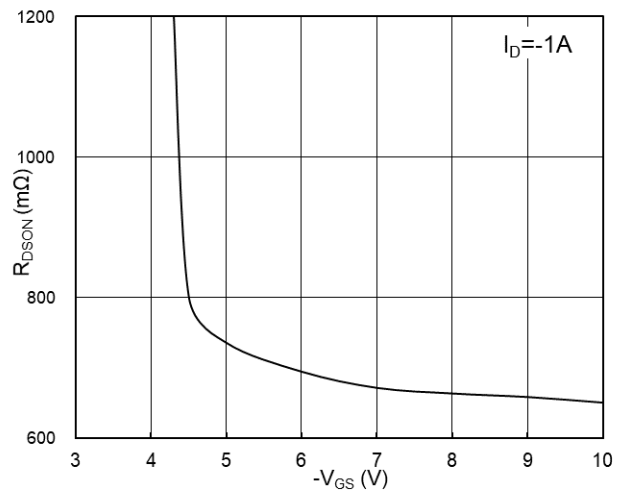
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=-50V, V_{GS}=-10V, L=1mH, I_{AS}=-5A$
- 4.The power dissipation is limited by 150 $^\circ C$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications , should be limited by total power dissipation.

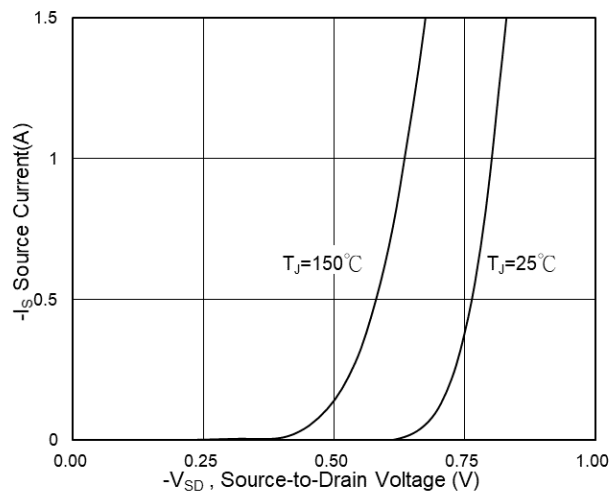
**Typical Characteristics**



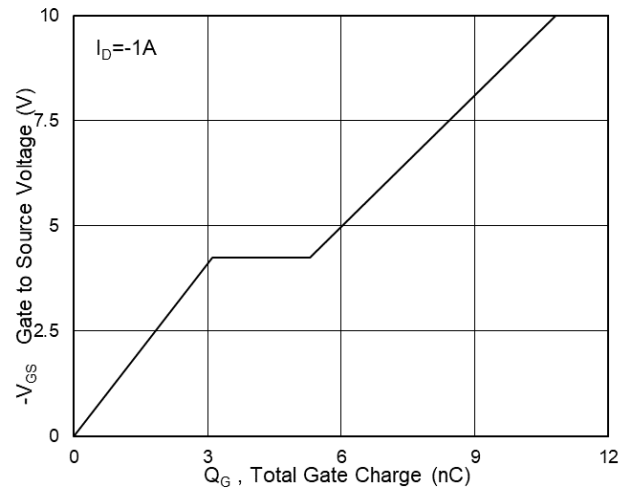
**Fig.1 Typical Output Characteristics**



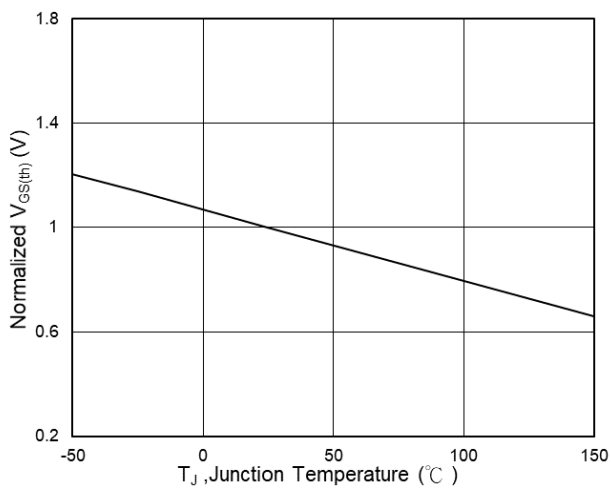
**Fig.2 On-Resistance vs G-S Voltage**



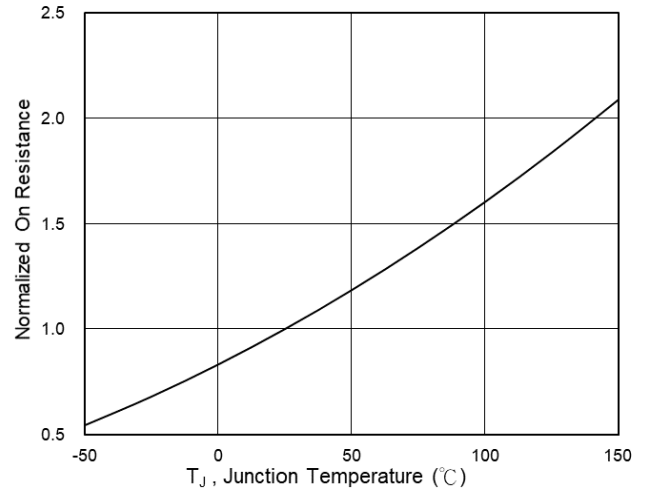
**Fig.3 Source Drain Forward Characteristics**



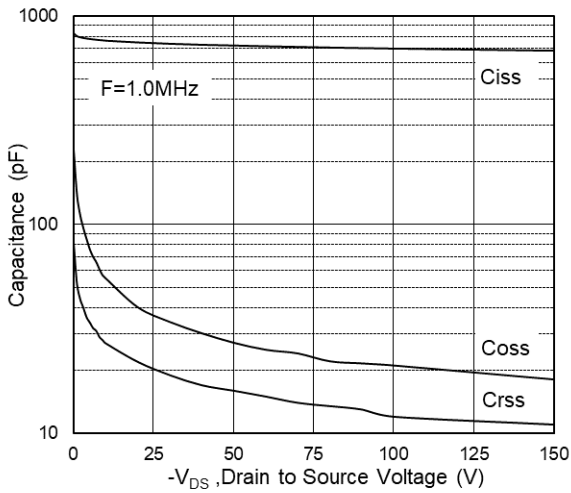
**Fig.4 Gate-Charge Characteristics**



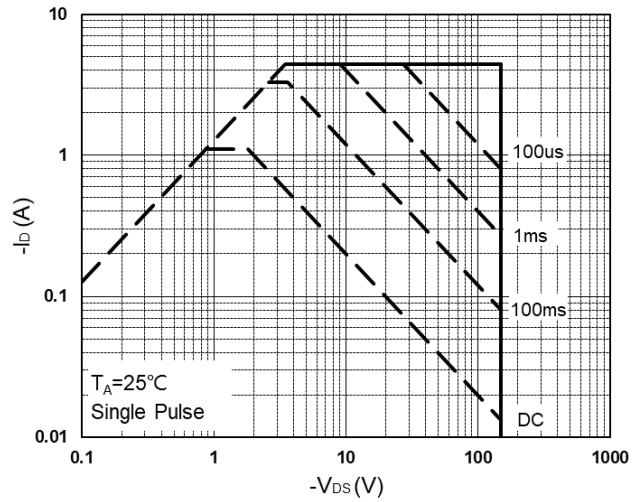
**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



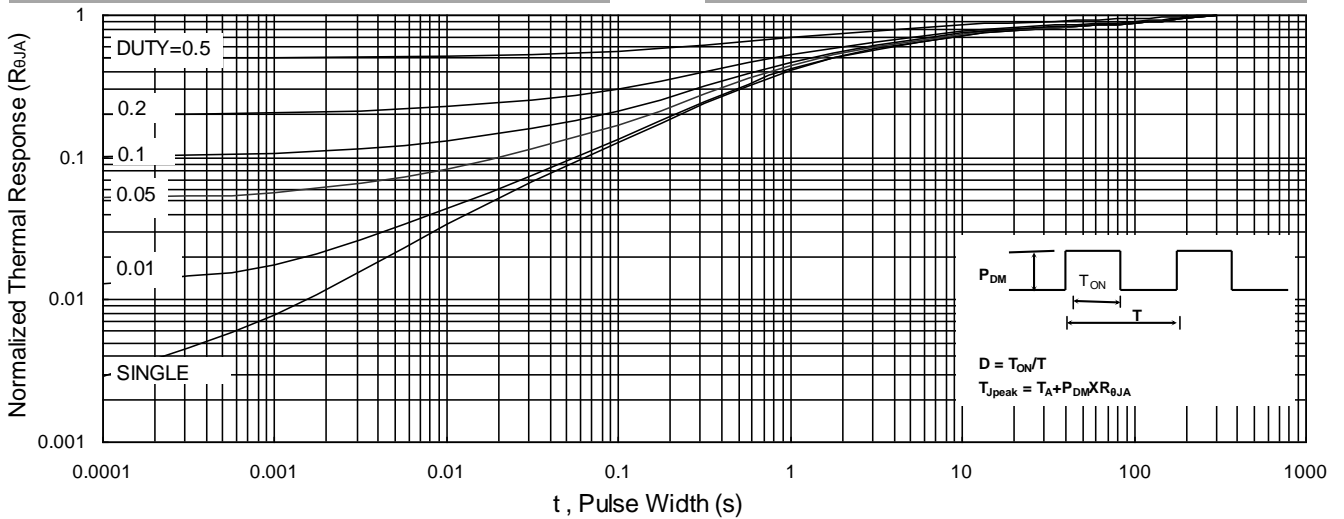
**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



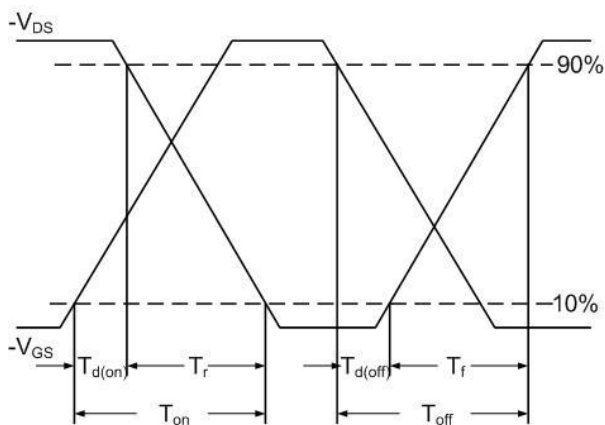
**Fig.7 Capacitance**



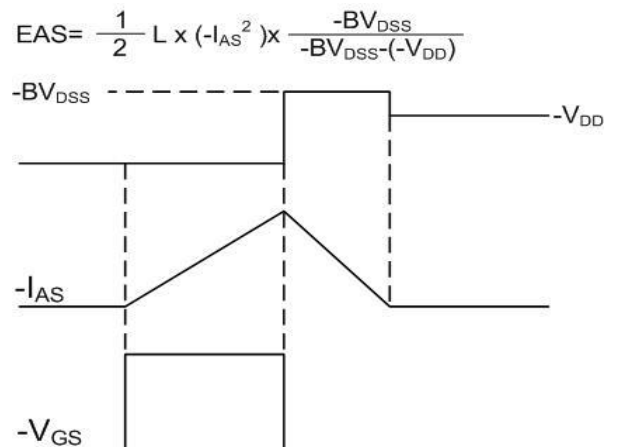
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**